

ABSTRACT**MULTI-LAYER PRINTED CIRCUIT BARE BOARD
ENABLING HIGHER DENSITY WIRING AND
A METHOD OF MANUFACTURING THE SAME**

5 With a multi-layer printed circuit bare board
(1) has $2n$ circuit layers, where n is a natural number
exceeding a unity, electrical connections are
established between the $(2i-1)$ -th layer (3, 21) and the
2i-th layer (5, 19), where $i=1, 2, \dots, n$, by holes (37)
10 which are created through insulation material layers
(35) in between and filled with copper plating (39).
Electrical connections are also accomplished between
the 4i-th layer (13, 19) and the $(4i-3)$ -th layer (3,
29) by holes (41) created through insulation material
15 layers (35) in between and filled with copper plating
(39). Higher dimensional accuracy and fewer process
steps are achieved.

20 FIG. 1